

FIG. 1

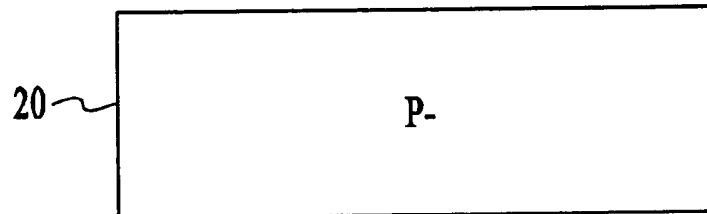


FIG. 2A

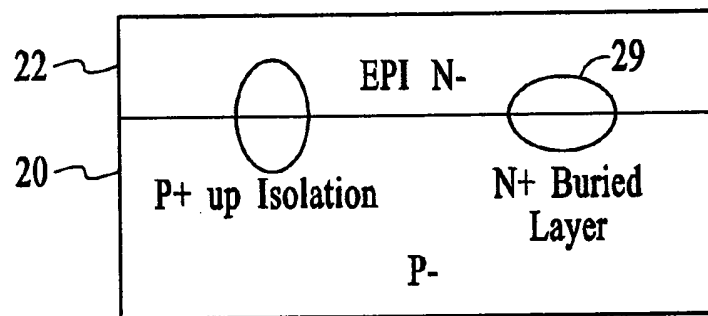


FIG. 2B

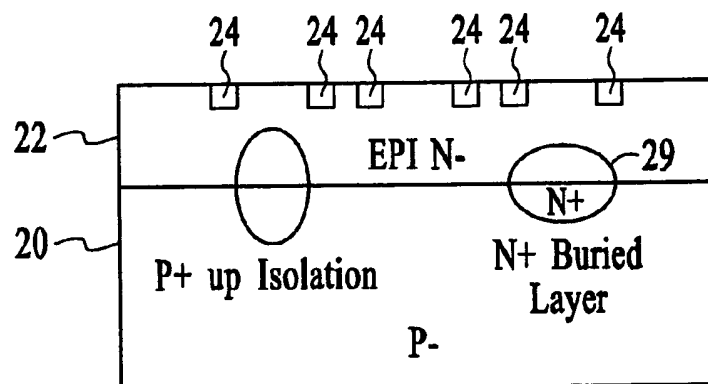


FIG. 2C

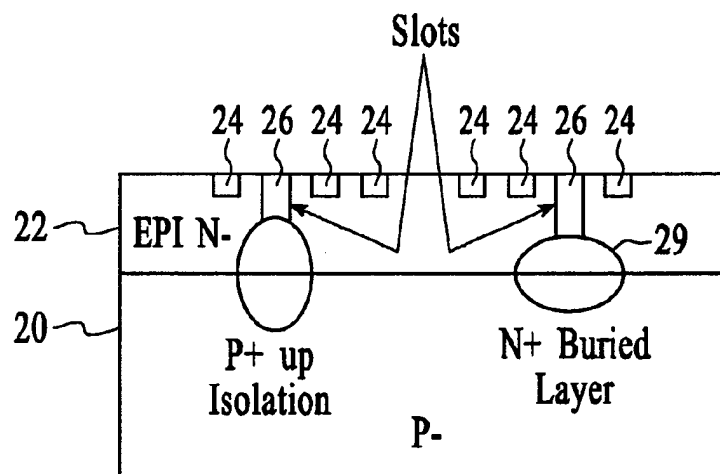


FIG. 2D

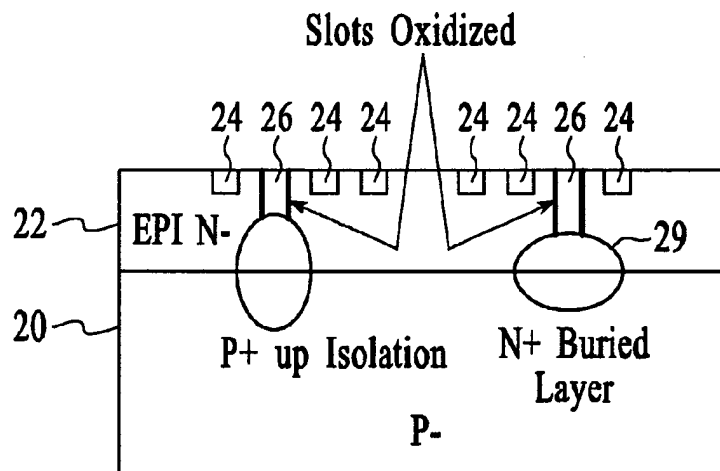


FIG. 2E

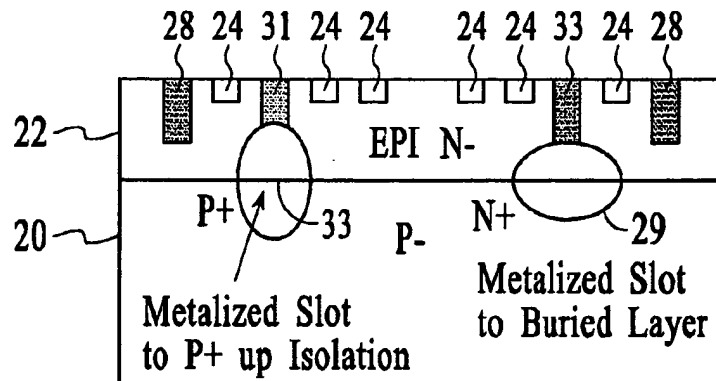


FIG. 2F

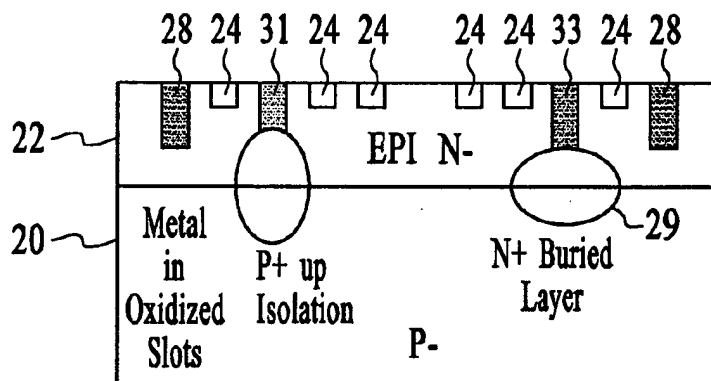
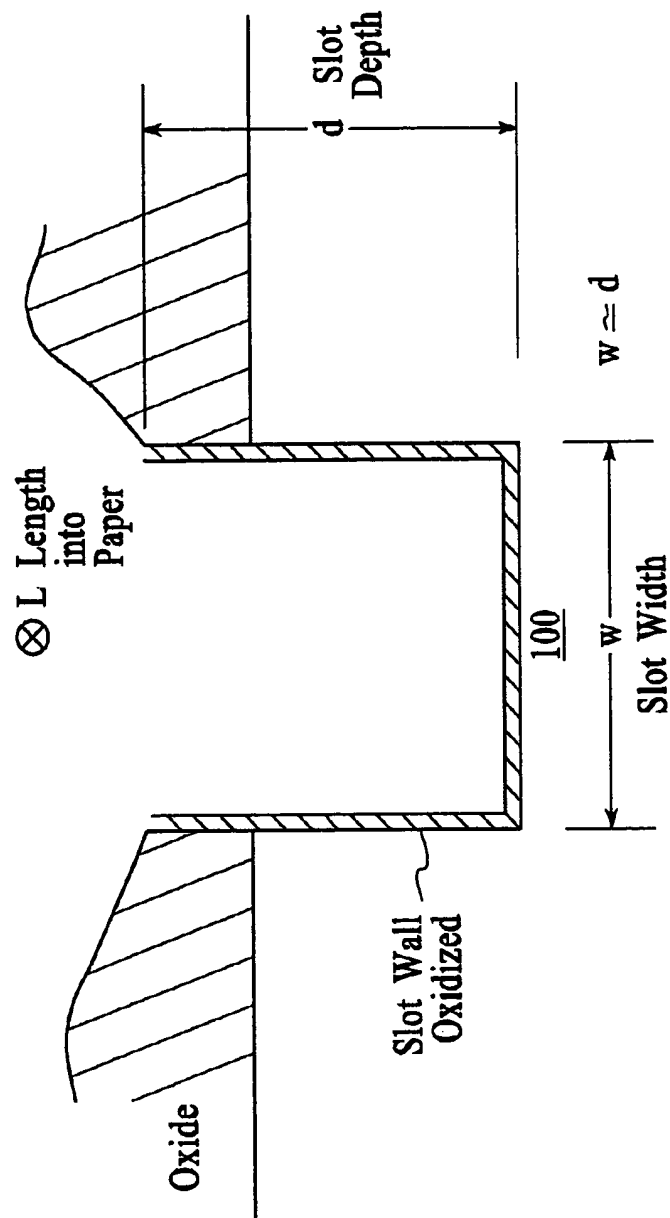
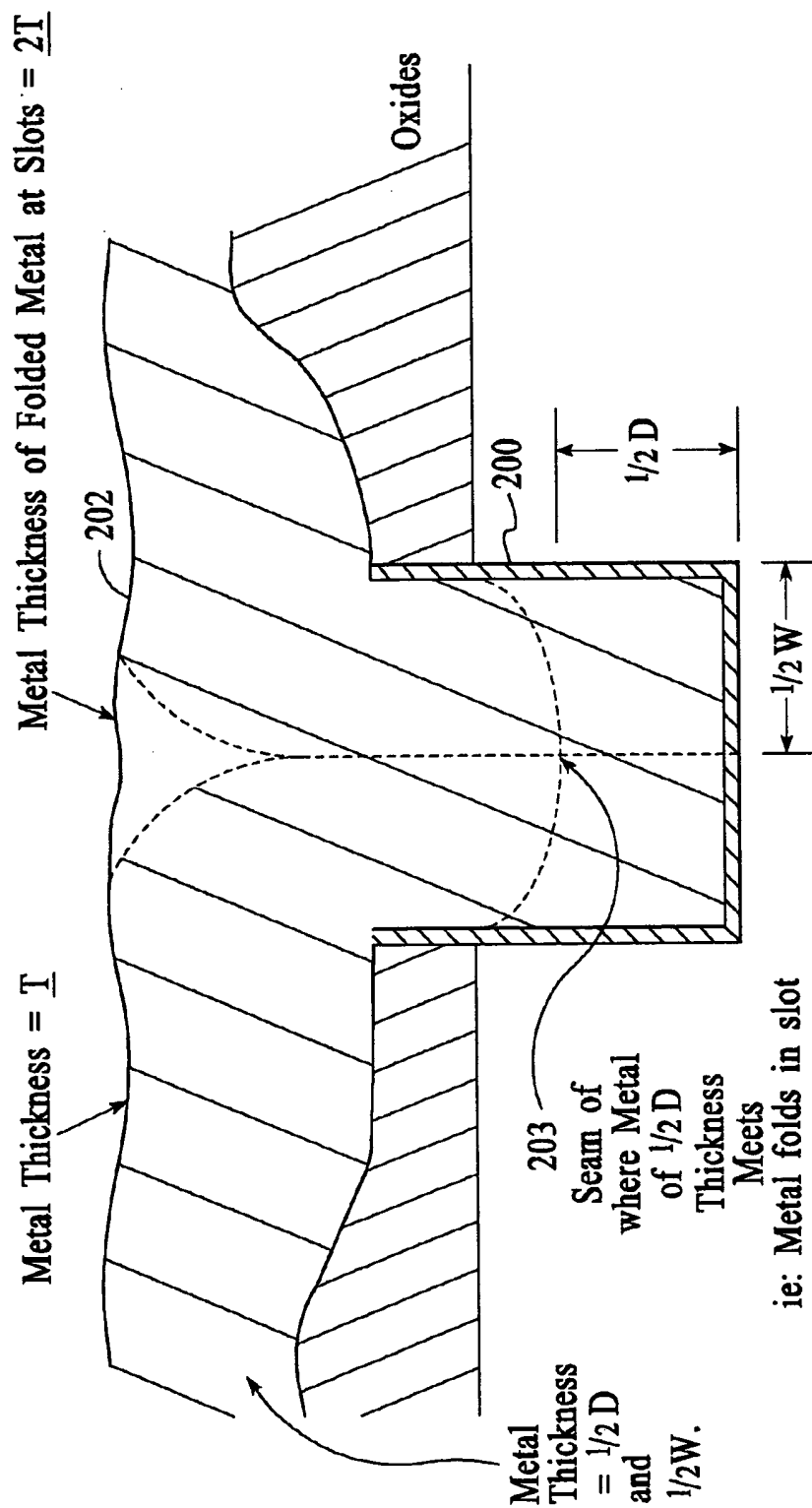


FIG. 2G



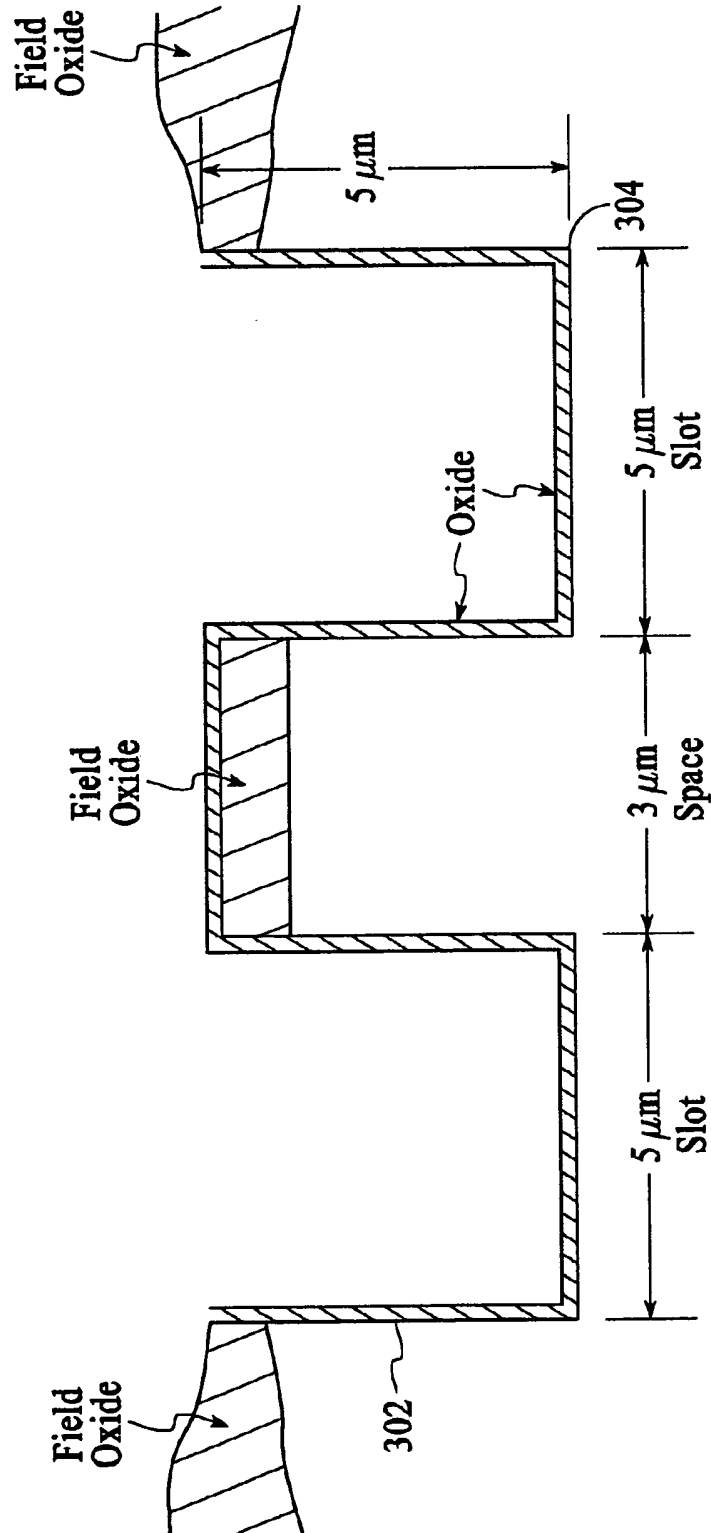
Typical Oxidized Slot showing Width (W) equal to depth (D)

FIG. 3



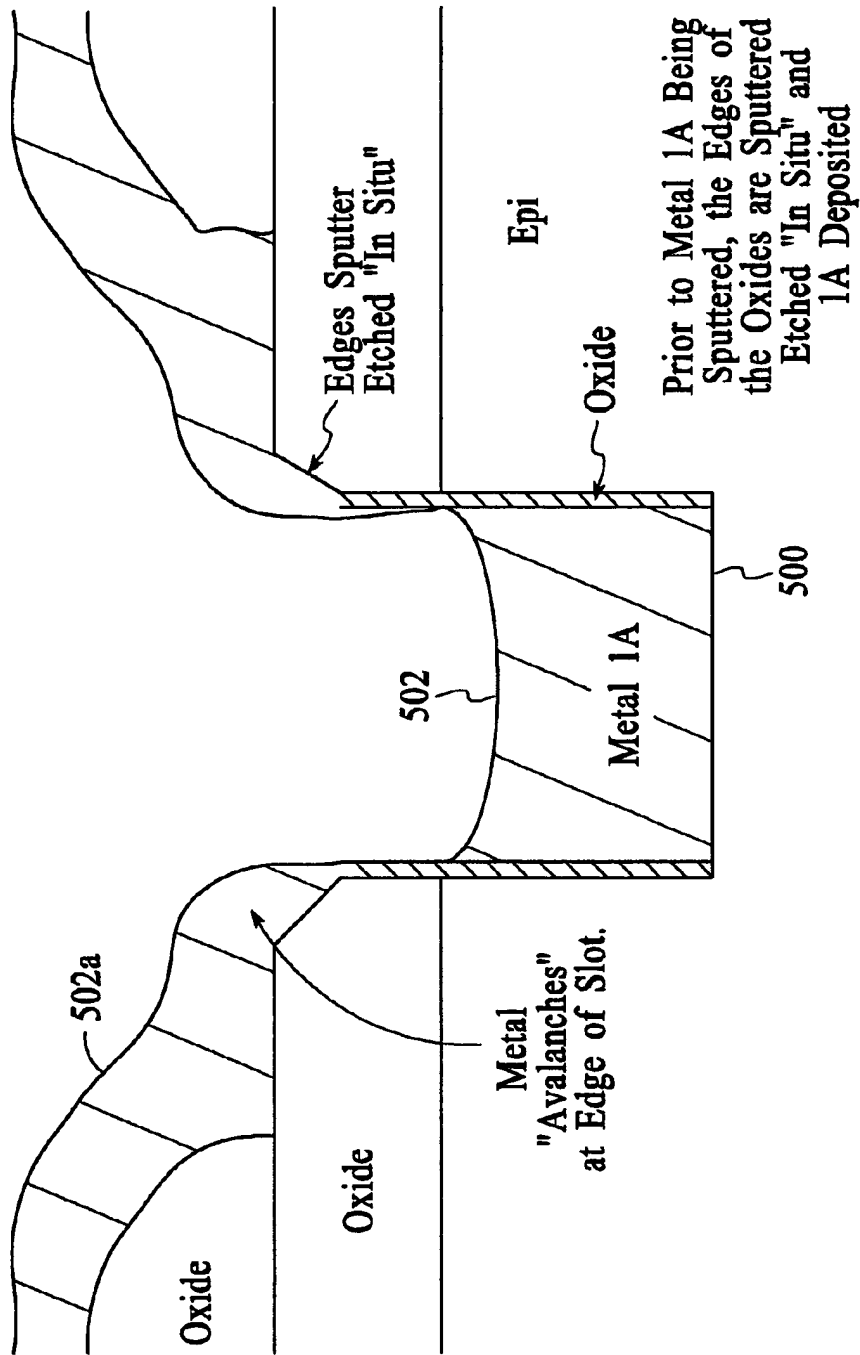
### Metal Folding in Slot to give double Thickness of Metal at Slots

**FIG. 4**



Double Slot for  
Double Width of Metal  
 $3\ \mu\text{m}$  Space Between Slots

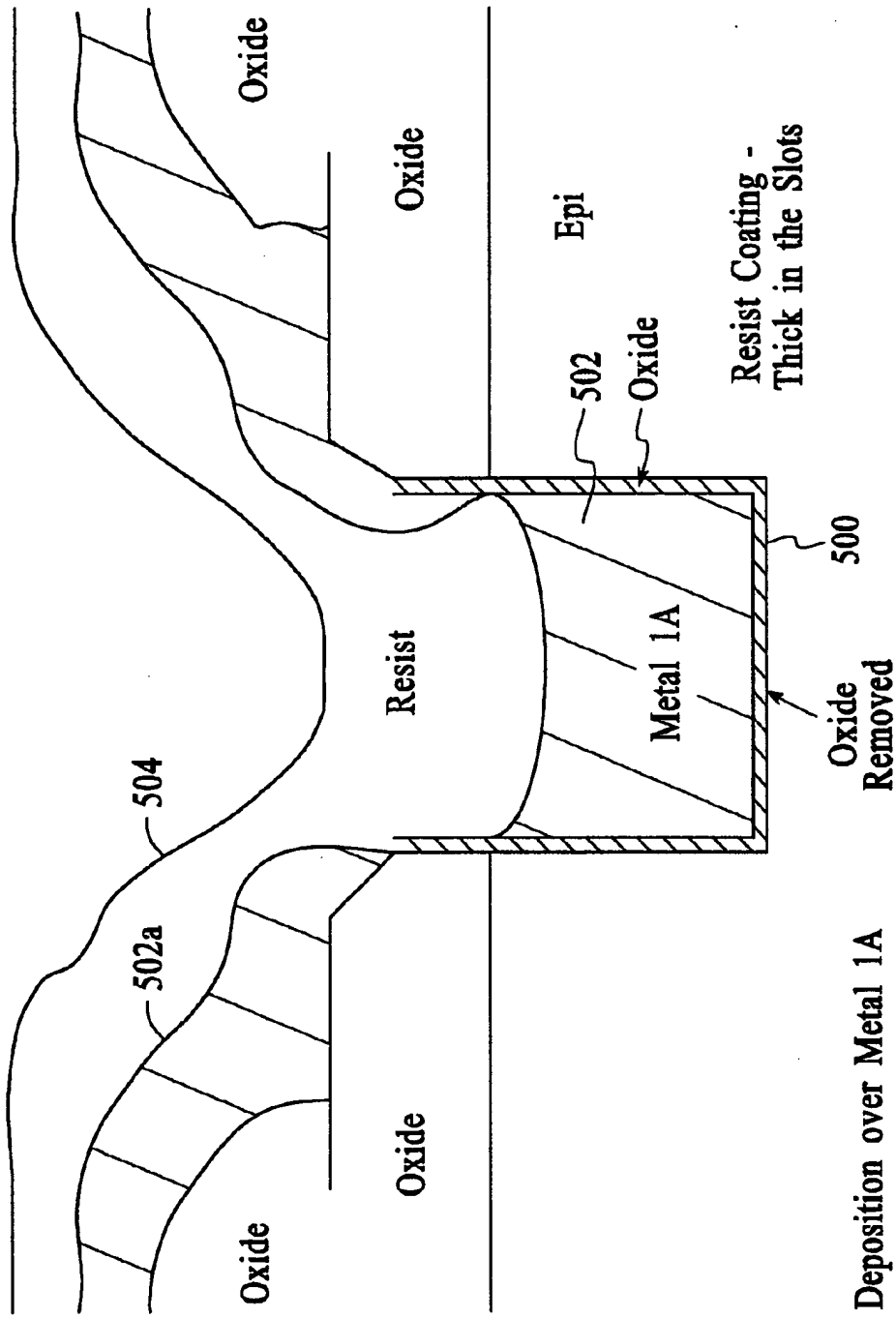
FIG. 5



After Metal 1A Deposition

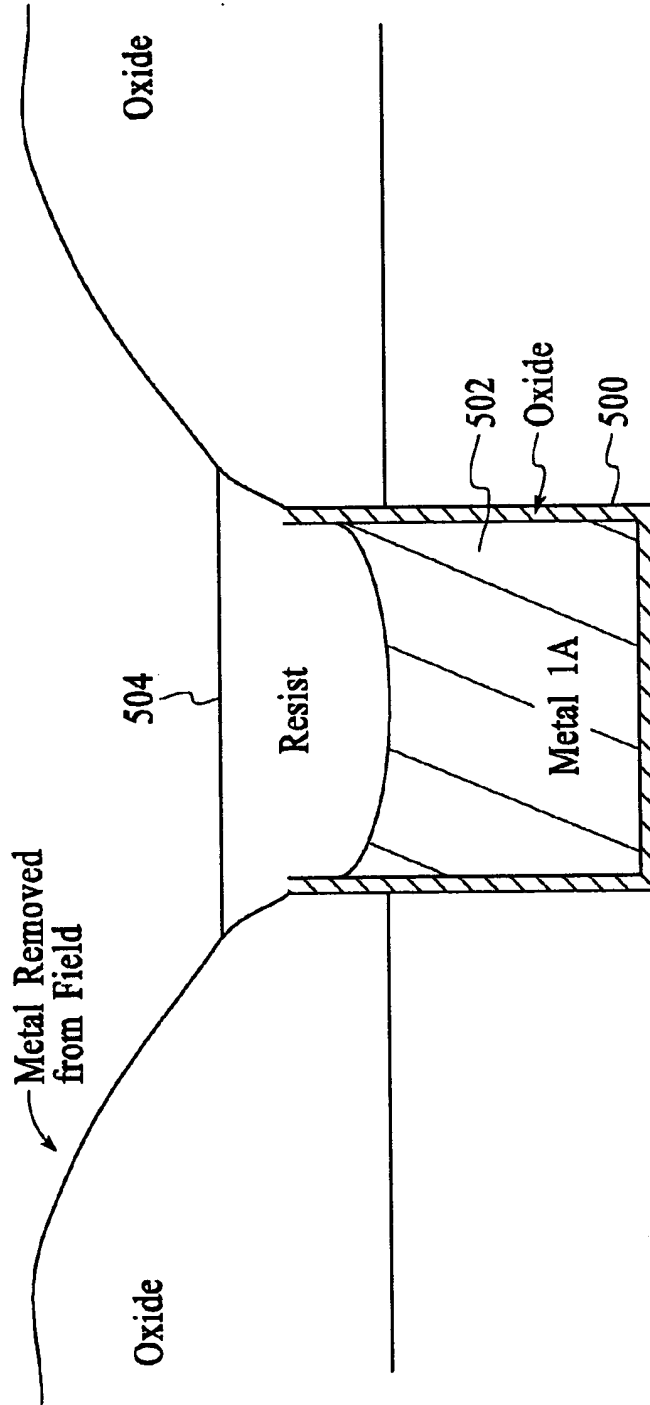
FIG. 6





Resist Deposition over Metal 1A

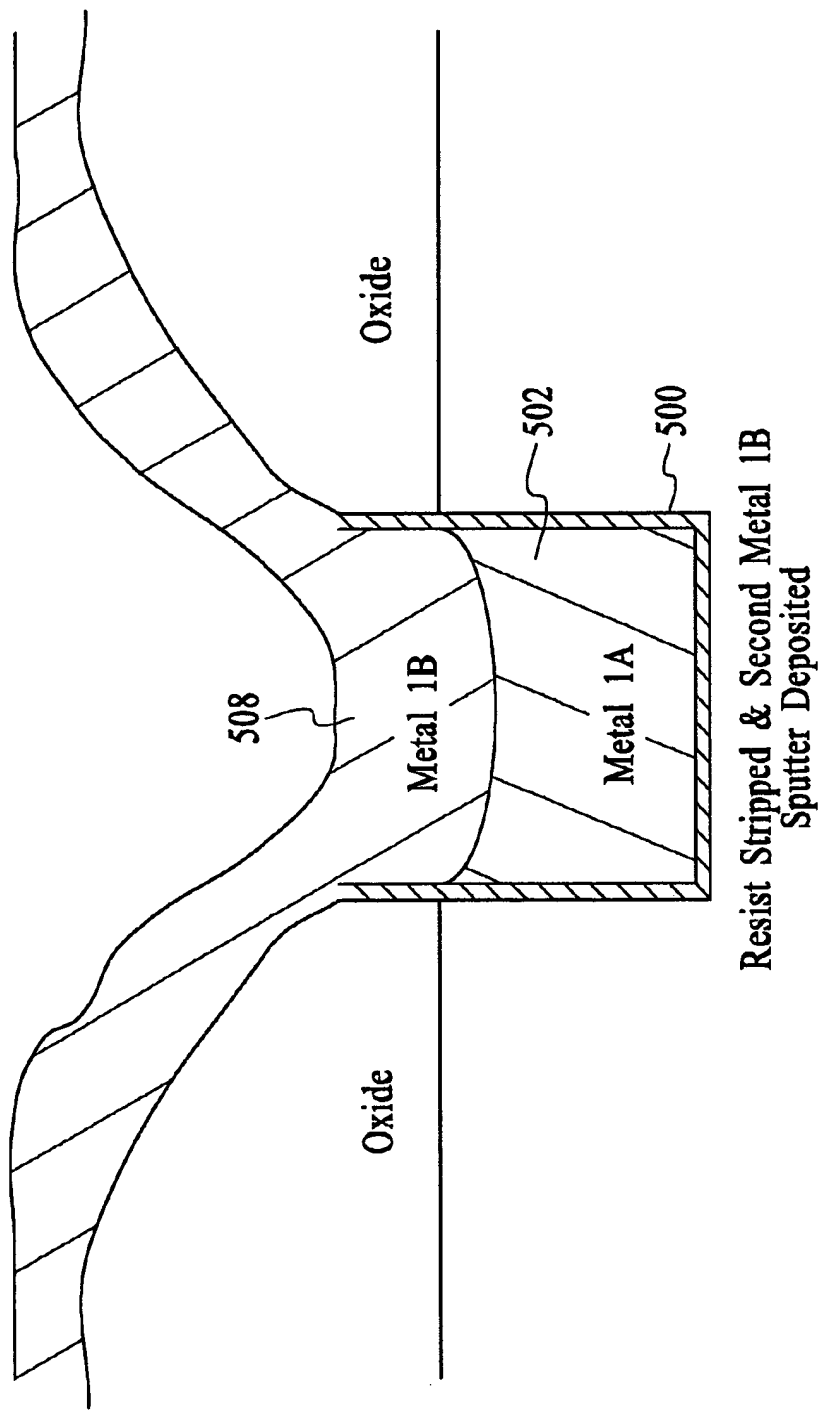
FIG. 7



Resist Planar Etched Leaving Resist  
in Slots. Field Metal Etched Off.

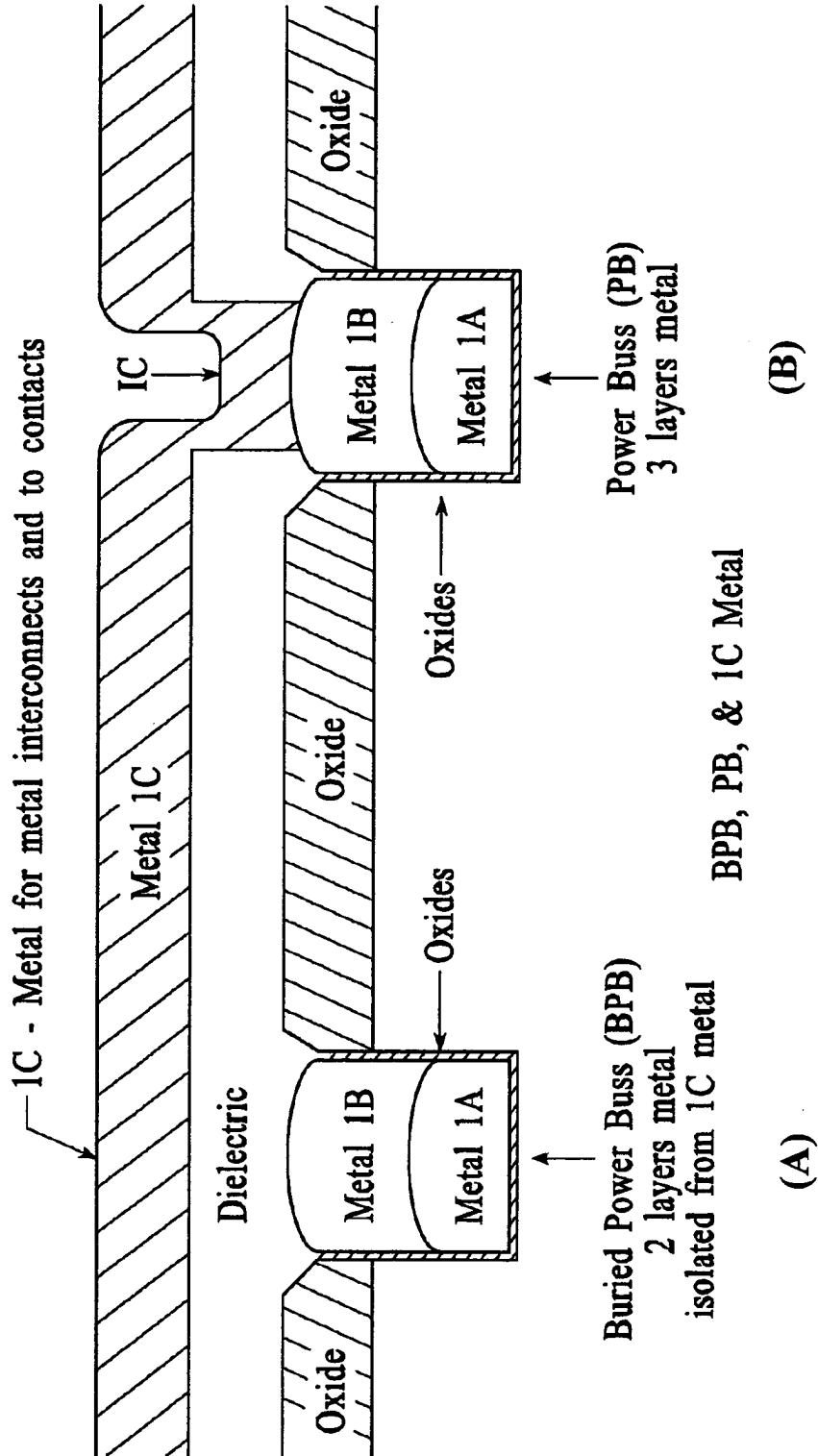
After Planarization - Metal Removed from Field (no masking)  
Some Resist remains in Slot areas and is Resist Stripped

FIG. 8



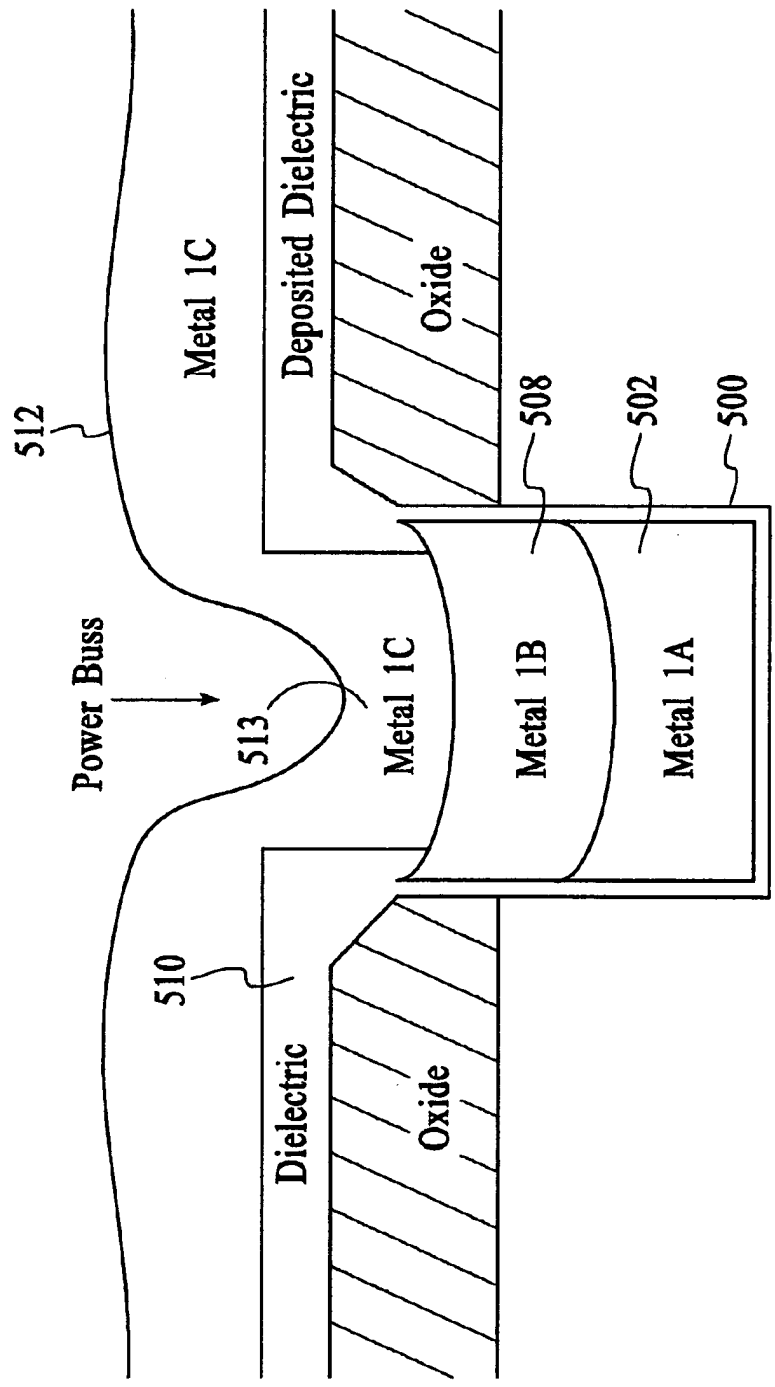
Metal 1B Deposited over Wafer

FIG. 9



Triple Metal & only 1C Metal Patterned

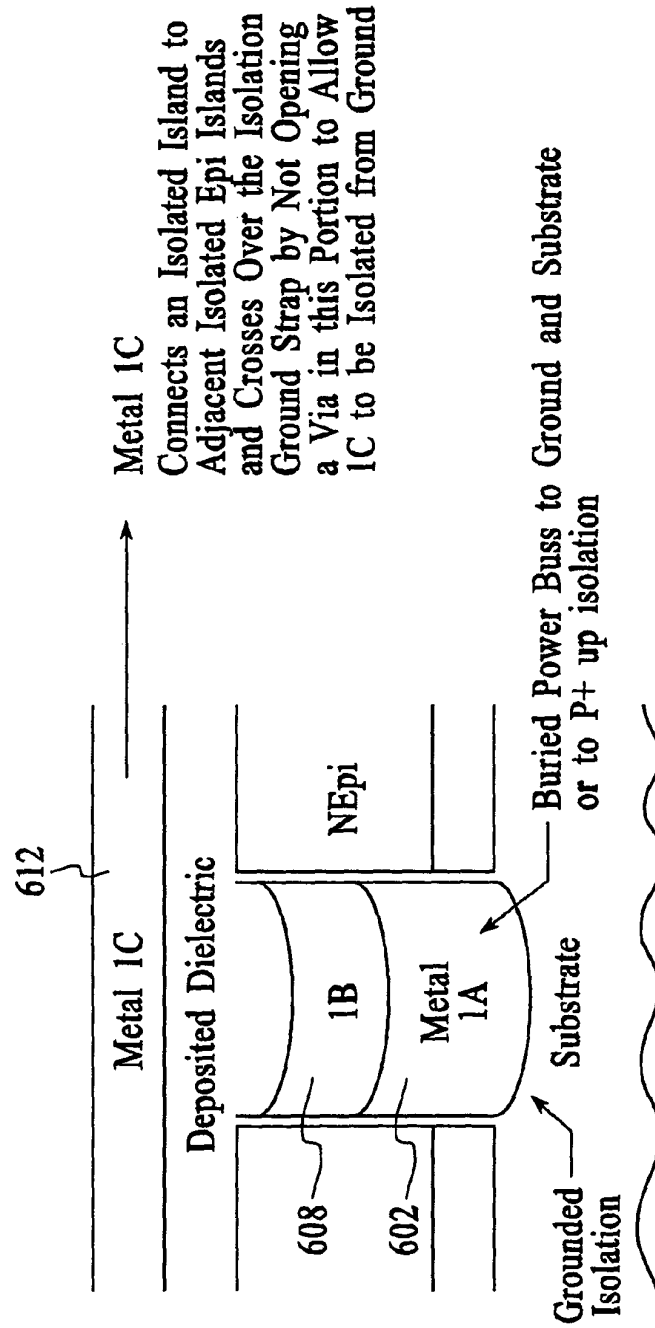
FIG. 10



Metal (3 layers - 1A, 1B, 1C) Shown in Power Buss

FIG. 11





Buried Power Buss to Ground. Isolated from 1C Metal which Interconnects Active, Positive Area, and Power Buss

FIG. 13